

Lenovo P340 Tiny

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Product Name	P340 Tiny
Product Display Name	ThinkStation P340 Tiny
Information Date	1-Sep-22
Hardware Maintenance Manual	P340 Tiny HMM
Drivers & Software	P340 Drivers & Software
Available Whitepapers	P340 Whitepapers

SECTION I: Platform Overview

Description	Innovative, Intelligent, and Inspiring: Go big with the P340 Tiny. The industry's smallest workstation, at less than one liter in total volume, offers uncompromising performance in a form factor that is 96% smaller than a traditional desktop. Display it on your desk, mount it behind your display, or carry it with you between locations while you experience the ultimate flexibility with a system that focuses on power, functionality, and configurability. Perfect for finance, higher education, architecture and engineering, and more, the P340 Tiny supports the fastest CPU, memory, and storage on the market, passes 18 MIL-STD tests ⁸ and features an optional dust filter for the ultimate in robust computing.
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CPU

Processor Support	Intel Comet Lake Core
Socket Type	Socket-H4 (LGA 1200)

Operating Systems

Preloaded	Windows 10 Pro 64-bit Windows 10 Home 64-bit Ubuntu 20.04 LTS (configuration specific)
Supported	Ubuntu 20.04 LTS Red Hat Enterprise Linux 8.2

Memory

Slots	Up to 2 SODIMMs
Channels	Supports up to 2 SODIMM Sockets, 2 Channels
Type	260-Pin, 2933MHz non-ECC SODIMM

ECC Support	No
Speed	Up to 2933MHz
Max DIMM Size	32GB DDR4 SODIMM
Max System Memory	64GB

Storage

Total Bays/Size	1 x 2.5"
PCIe	2 x M.2 PCIe Connectors, Gen 3 Onboard
Disclaimers	Additional parts/enclosures may be required for some configurations

Video

Integrated Graphics	Intel Integrated UHD Graphics 630
Discrete Graphics	PCIe Add-In-Card, Details in Section Below
Multi-GPU Support	Yes
Type	PCIe Add-In-Card
Bus Interface	PCIe x8 Gen 3 Routed From CPU

Front I/O

USB	1 x USB 3.2 Gen 2 Type-A 1 x USB 3.2 Gen 1 Type-C
Audio	1 x Combo Audio/Microphone Jack (3.5mm)

Rear I/O

USB	2 x USB 3.2 Gen 2 Type-A 2 x USB 3.2 Gen 1 Type-A
DisplayPort	1 x Standard Optional 1 x Rear Port
HDMI	1 x Standard Optional 1 x Rear Port
VGA Port	Optional 1 x Rear Port
Serial Port	Optional 2 x Rear Port
Ethernet	1 x 1GbE – RJ45
Optional USB Adapter	Single Type-C + DP Port
Optional Network Adapter	Intel I350-T2 Dual Port Gigabit Ethernet Adapter Intel I350-T4 Quad Port Gigabit Ethernet Adapter

Ethernet

Vendor	Intel Jacksonville I219LM
Speeds	10/100/1000Mbps
Functions	PXE, ASF, WoL, Jumbo Frames, Teaming

Connectors	1 x RJ45
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Audio

Vendor	Realtek
Type	Integrated Audio
Internal Speaker	Yes
Connectors	Mic + Headphone combo jack
Chipset	ALC233VB
Number of Channels	2 Channels
Number of Bits/Audio Resolution	2 Channels of DAC support 24-bit PCM format

Thermal

Temp Sensors	Ambient Sensor VR Sensor M.2 Sensor
Fans	1 x CPU Fans

Power Specifications

Power Supply	170W/230W
Power Efficiency	89% Efficient @ 50% Load
Operating Voltage Range	100 – 240V
Rated Voltage Range	90-264VAC
Rated Line Frequency	47Hz / 63Hz
Operating Line Frequency Range	50Hz / 60Hz
Rated Input Current	6.75A
Graphics	No
Power Supply Fan	No
ENERGY STAR® Qualified (config dependent)	Yes
Aux Power Drop	No

BIOS

Vendor	AMI
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Chassis Information

Color	Raven Black
PSU	230W Power Brick (Chicony, A18-230P1A) Dimensions: 200*100*25.4mm Weight: 878.8g 170W Power Brick (Delta, ADP-170CB) Dimensions: 155*76*30mm Weight: 586.7g
Thermal Solutions	One System Fan Standard

Dimensions	179mm/7.047" H 182.9mm/7.2" D 36.5mm/1.437" W
Weight	1.32kg / 2.91lbs

Packaging Dimensions

Height (mm/in)	179mm / 7"
Width (mm/in)	37mm / 1.5"
Depth (mm)	182.9mm / 7.2"
Weight (kgs/lbs)	1.4kg / 3lbs

Security & Serviceability

TPM	Infineon SLB9670, FW 7.85, TPM 2.0
Asset ID	Yes, 1024 x 8bit
vPro	Intel vPro for WS (AMT 14.X)
Cable Lock Support	Yes, Optional Kensington Cable Lock
Serial, Parallel, USB, Audio, Network, Enable/Disable Port Control	Yes
Power-On Password	Yes
Setup Password	Yes
NIC LEDs (integrated)	Yes
Access Panel Key Lock	No
Boot Sequence Control	Yes
Padlock Support	No
Boot without keyboard and/or mouse	Yes
Access Panel	Tool-less Side Cover Removal
Hard Drives	Tool-less
Expansion Cards	Retained With Screws
Processor Socket	Tool-less
Color coded User Touch Points	Yes
Color-coordinated Cables and Connectors	Yes
Memory	Tool-less
System Board	Retained With Screws
Restore CD/DVD/USB Set	Not Included, Restore Media Available via Lenovo Customer Support Center

Operating Environment

Air Temperature	Operating: 5°C to 35°C (41°F to 95°F)
Storage	Storage: -40°C to 60°C (-40°F to 140°F) in Original Shipping Carton Storage: -10°C to 40°C (14°F to 104°F) Without Carton
Humidity	Relative Humidity Operating: 10% to 90% (non-condensing) Relative Humidity Storage/Transit: 10% to 90% (non-condensing)

	Wet Bulb Temperature Operating: 25°C (77°F) max Wet Bulb Temperature Non-operating: 40°C (104°F) max
Altitude	Operating: 0m to 3048m (0ft to 10000ft) Storage: 0m to 12192m (0ft to 40000ft)
Vibration	Package Vibration: Random,1.04G at 2-200 Hz, 15 Minutes XYZ 6 faces Operating Vibration: Random,0.27G at 5-500 Hz, 30 Minutes Per Surface (X,Y,Z) Non-Operating Vibration: Random,1.04G at 2-200 Hz, 15 Minutes Per Surface (±X,±Y,±Z)
Shock	Operation Shock: 3ms (15G) for 4 Axis (+X, -X, +Y,-Y) 3ms (30G) for 2 Axis (+Z, -Z), Half-sine Wave, Each Side Will do One Time Rack Operation Shock: 5ms (15G) for 6 Axis (+X, -X, +Y,-Y,+Z, -Z), Half-sine Wave, Each Side Will do One Time Non-operating Shock: Trapezoidal Wave, 45G, 11ms, 6 Sides (+X, -X, +Y,-Y, +Z, -Z), Filter 300Hz, Each Side Shock One Time

SECTION II: Platform Detail

Board Size	6.75" x 6.89" (171.5mm x 175mm)
Layout	Custom ATX

Motherboard Core

Processor Support	Intel Comet Lake Core
Socket Type	Socket-H4 (LGA 1200)
Memory Support	DDR4 up to 2933MHz SODIMM Memory
Voltage Regulator	65W TDP Capable
Chipset (PCH)	Intel Q470 Chipset
Flash	32MB
Super I/O	Nuvoton NCT6686D-L
Clock	Intel Native isCLK
Audio	Realtek ALC233VB Codec
Ethernet	Intel Jacksonville I219LM

Supported Components

Processor Level	Intel Comet Lake Core
Processor	i9-10900 i7-10700 i5-10600 i5-10500 i5-10400 i3-10320 i3-10300 i3-10100 i9-10900T i7-10700T i5-10600T i5-10500T i5-10400T i3-10300T i3-10100T
Memory Type	SODIMM 2933 MHz

Memory	4GB 2933MHz DDR4 SDRAM SODIMM 8GB 2933MHz DDR4 SDRAM SODIMM 16GB 2933MHz DDR4 SDRAM SODIMM 32GB 2933MHz DDR4 SDRAM SODIMM
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Storage

M.2 PCIe Solid State Drive (SSD)	256GB M.2 PCIe SSD, Gen 3 x4, NVMe, OPAL 512GB M.2 PCIe SSD, Gen 3 x4, NVMe, OPAL 1024GB M.2 PCIe SSD, Gen 3 x4, NVMe, OPAL 2048GB M.2 PCIe SSD, Gen 3 x4, NVMe, OPAL
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RAID

Notes	Supported RAID levels for a system will vary from the stated capabilities of the RAID controller due to dependencies on the number and capacity of physical disks in the system and on customer requirements for performance, fault tolerance, or data redundancy. Max supported RAID 0/1.
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Optical Drive/Removable Media

DVD-ROM Drive	Slim DVD-ROM Drive
DVD Burner/CD-RW Drive	Slim DVD Burner/CD-RW Drive

Keyboard and Pointing Devices

Keyboard	Traditional USB Keyboard Calliope Wireless Keyboard
Pointing Devices	Calliope USB Mouse Calliope Wireless Mouse Fingerprint USB Mouse

PCIe Adapters

Network	Intel I350-T2 Dual Port Gigabit Ethernet Adapter Intel I350-T4 Quad Port Gigabit Ethernet Adapter
Thunderbolt	Rear Thunderbolt PCIe Adapter
WiFi Cards	Intel PCIe WiFi Card With BT External Antenna Kit (Intel AX201 vPro) Intel PCIe WiFi Card With BT External Antenna Kit (Intel 9560 non-vPro) Foxconn PCIe WiFi Card with BT External Antenna Kit (Foxconn RTL8822CE non-vPro)

SECTION III: Supported Component Detail

CPU Specifications Part 1

CPU	Intel i3-10320	Intel i3-10100	Intel i3-10300	Intel i5-10400	Intel i5-10500
# of Cores	4c	4c	4c	6c	6c

# of Threads	8	8	8	12	12
Processor Base Frequency	3.8GHz	3.6GHz	3.7GHz	2.9GHz	3.1GHz
Max Turbo Frequency	NA	NA	NA	NA	NA
Cache	8M	8M	8M	12M	12M
TDP	65W	65W	65W	65W	65W

CPU Specifications Part 2

CPU	Intel i5-10600	Intel i7-10700	Intel i9-10900	Intel i3-10100T	Intel i3-10300T
# of Cores	6c	8c	10c	4c	4c
# of Threads	12	16	20	8	8
Processor Base Frequency	3.3GHz	2.9GHz	2.8GHz	3.0GHz	3.0GHz
Max Turbo Frequency	NA	4.8GHz	5.1GHz	NA	NA
Cache	12M	16M	20M	8M	8M
TDP	65W	65W	65W	35W	35W

CPU Specifications Part 3

CPU	Intel i5-10400T	Intel i5-10500T	Intel i5-10600T	Intel i7-10700T	Intel i9-10900T
# of Cores	6c	6c	6c	8c	10c
# of Threads	12	12	12	16	20
Processor Base Frequency	2.0GHz	2.3GHz	2.4GHz	2.0GHz	1.9GHz
Max Turbo Frequency	NA	NA	NA	4.5Ghz	4.6GHz
Cache	12M	12M	12M	16M	20M
TDP	35W	35W	35W	35W	35W

Solid State Storage Specifications

Drive	NVMe 2280 M.2 256GB PCIe SSD (OPAL)	NVMe 2280 M.2 512GB PCIe SSD (OPAL)	NVMe 2280 M.2 1TB PCIe SSD (OPAL)	NVMe 2280 M.2 2TB PCIe SSD (OPAL)
Dimensions Millimeters (W x D x H)	22 x 80 x 3	22 x 80 x 3	22 x 80 x 3	22 x 80 x 3
Interface Type	PCIe Gen 3x4	PCIe Gen 3x4	PCIe Gen 3x4	PCIe Gen 3x4
Power Active (AVG)	5.0W	5.0W	5.0W	5.0W
Power Idle	50 mW	50 mW	50 mW	50 mW
Typical Sequential Read	3000 MB/s	3100 MB/s	3200 MB/s	3200 MB/s
Typical Sequential Write	1600 MB/s	2700 MB/s	2900 MB/s	2700 MB/s
Operating Temperature Range	0 to 55°C	0 to 55°C	0 to 55°C	0 to 55°C
Endurance Rating (Lifetime Writes)	85 TB	150 TB	300 TB	600 TB
Mean Time Between Failures (MTBF)	2.0M POH	2.0M POH	2.0M POH	2.0M POH

Hardware Encryption	AES 256 bit	AES 256 bit	AES 256 bit	AES 256 bit
Disclaimers		SSD performance measured with Crystal Disk Mark version 6.0.2 with the default 1000 MB data set. Sequential measurements are with 1 Thread, Queue-Depth 32. Random measurements are with 4 threads and queue-depth 32.		

Optical Drive Specifications

Description	9mm Slim DVD ROM Drive (SATA)- Win10	9mm Slim DVD Burner/CD-RW Drive (SATA)- No OS/Linux
Interface Type	SATA 1.5 Gb/s	SATA 1.5 Gb/s
Dimensions	128±0.4×9.0 ±0.4×127±0.4(Max) Unit:mm (Without Bezel-W x H x D)	128±0.4×9.0 ±0.4×127±0.4(Max) Unit:mm (Without Bezel-W x H x D)
Disc Capacity	NA	NA
Type	DVDROM	DVDWriter
External Dimensions	NA	NA
Speed	NA	NA
Bay Type	9.0mm Tray	9.0mm Tray
Color	Business Black or without bezel	Business Black or without bezel
Removable	No	No
Internal Buffer Size	0.5MB Min	0.5MB Min
Writes	NA	8XDVD+R / 8XDVD+RW / 6XDVD+R DL 8XDVD-R / 6XDVD-RW / 6XDVD-R DL 24XCD-R / 16XCD-RW
Reads	8XDVD-ROM / 24XCD-ROM	8XDVD-ROM / 24XCD-ROM
Source	DC Power 5V	DC Power 5V
DC Power Requirements	+5V±5%	+5V±5%
DC Current	Max 2.5A@5v	Max 2.5A@5v
Operating Systems Supported	All Windows OS	All Windows OS
Temperature	Operating: 5°C to 45 °C Non-Operating:-30°C to 60°C	Operating: 5°C to 45 °C Non-Operating:-30°C to 60°C
Relative Humidity	Operating > Read: 15 % to 85 % (Non-Condensing) Write 15 % to 80 % (Depend on the Temperature) Storage/Transportation> 10 % to 80 % (Non-Condensing)	Operating > Read: 15 % to 85 % (Non-Condensing) Write 15 % to 80 % (Depend on the Temperature) Storage/Transportation> 10 % to 80 % (Non-Condensing)

Integrated Graphics Adapter

Type	Intel UHD Graphics 630
Display Interface	1 x DP 1.2, 1 x HDMI 1.4
Video Resolution (max)	4096×2304 @ 60Hz (DP), 4096×2304 @ 24Hz (HDMI)

Discrete Graphics Adapter

Adapter	Quadro P620	Quadro P1000
Bus Interface	PCIe 3.0 x16	PCIe 3.0 x16
Display Interface	4 x mDP 1.4	4 x mDP 1.4
Graphics Chipset	Pascal	Pascal

Memory Clock Frequency (MHz)	1252MHz	1253MHz
Memory Size	2GB GDDR5	4GB GDDR5
Memory Interface	128-bit	128-bit
Memory Bandwidth	Up to 80GB/s	Up to 82GB/s
GPU Cores	CUDA Cores: 512	CUDA Cores: 640
GPU Core Frequency (MHz)	1266MHz	1266MHz
Maximum Power Consumption	40W	47W
Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or Digital)	4 x 4096x2160 @ 60Hz 4 x 5120x2880 @ 60Hz	4 x 4096x2160 @ 60Hz 4 x 5120x2880 @ 60Hz
Thermal Solution	Ultra-quiet Active Fansink	Ultra-quiet Active Fansink
Dimension	2.713" H x 5.7" L Single Slot, Low Profile	2.713" H x 5.7" L Single Slot, Low Profile

Ethernet Specifications Group 1 Part 1

Card	Intel Jefferson Peak 2 9560 2*2ac+BT5.0 PCIE Non-vPro M.2 Module (CNVi)	Intel Wi-Fi 6 AX201 2*2ax+BT5.0 vPro PCIE M.2 2230 Module (CNVi)	Foxconn RTL8822CE 2*2ac+BT5.0 PCIE M.2 WLAN module	Intel I350-T2 Dual Port Gigabit Ethernet Adapter (Stony Lake T2)	Intel I350-T4 Quad Port Gigabit Ethernet Adapter (Stony Lake T4)
Supplier PN	9560.NGWC.NV MM# 957715	AX201.NGWC MM# 985841	T99H152.00	I350T2G1P20, MM# 928941	I350T4G1P20, MM# 928942
Data Rates Supported	5G/2.4G WIFI	5G/2.4G WIFI	5G/2.4G WIFI	10/100/1000Mbps (Copper), 1000Mbps (Fiber)	10/100/1000Mbps (Copper), 1000Mbps (Fiber)
Controller Details	Coming Soon	Coming Soon	Coming Soon	Intel Ethernet Controller I350	Intel Ethernet Controller I351
Controller Bus Architecture	PCIe Gen3	PCIe Gen3	PCIe Gen3	PCIe 2.1 (5GT/s)	PCIe 2.1 (5GT/s)
Data Transfer Mode	Wireless +BT	Wireless +BT	Wireless +BT	Ethernet	Ethernet
Power Consumption	Coming Soon	Coming Soon	Coming Soon	Copper: I350-T2 V2= 4.4W Fiber: I350-F2= 5.5W	Copper: I350T4V2= 5W LC-Fiber: I350F4= 6W
IEEE Standards Compliance	802.11 abgn+acR2 MIMO 2X2 +MU-MIMO	802.11 abgn+acR2 +ax MIMO 2X2	802.11a/b/g/n/ac	IEEE 802.3/10BASE-T, 100BASE-TX, 1000BASE-T	IEEE 802.3/10BASE-T, 100BASE-TX, 1000BASE-T
Boot ROM Support	UEFI boot	Core boot UEFI boot	Coming Soon	PXE boot, Intel iSCSI Remote Boot for Windows, Linux and Vmware, Intel BootAgent Software via PXE or BootP, WDMS or UEFI	PXE boot, Intel iSCSI Remote Boot for Windows, Linux and Vmware, Intel BootAgent Software via PXE or BootP, WDMS or UEFI
Network Transfer Mode (Full/Half Duplex)	Supported	Supported	Coming Soon	Supported	Supported
Network Transfer Rate	Coming Soon	Coming Soon	Coming Soon	1,000Mbps Full Duplex	1,000Mbps Full Duplex
Operating System Driver Support	Windows 8.1, Windows 10, Linux, Chrome	Windows 10, Linux, Chrome	Windows 10	Windows 7/8/10, Linux, Free BSD, XEN,Vmware	Windows 7/8/10, Linux, Free BSD, XEN,Vmware
Manageability	Coming Soon	Coming Soon	Coming Soon	Supported	Supported
Manageability Capabilities Alerting	Coming Soon	Coming Soon	Coming Soon	Supported	Supported
TDP	Coming Soon	Coming Soon	Coming Soon	Firmware Based Thermal Management	Firmware Based Thermal Management

Operating Temperature Range	0°C – 80°C	0°C – 80°C	0°C – 70°C	0°C to 55°C (32°F to 131°F)	0°C to 55°C (32°F to 131°F)
# of Ports	Coming Soon	Coming Soon	Coming Soon	2	4
Data Rate Per Port	Coming Soon	Coming Soon	Coming Soon	10/100/1000Mbps (copper), 1000Mbps (fiber)	10/100/1000Mbps (copper), 1000Mbps (fiber)
System Interface Type	PCIe Gen3 x4	PCIe Gen3 x4	PCIe Gen3 x4	PCIe Gen 2.1	PCIe Gen 2.1
NC Sideband Interface	Coming Soon	Coming Soon	Coming Soon	Not Available	Not Available
Jumbo Frames Supported	Coming Soon	Coming Soon	Coming Soon	Yes	Yes
1000Base-T	Coming Soon	Coming Soon	Coming Soon	Yes	Yes
IEEE 1588	Coming Soon	Coming Soon	Coming Soon	Supported	Supported
Supported Under vPro	Not Available	Yes	Not Available	Not Available	Not Available

Ethernet Specifications Group 1 Part 2

Model	Intel I350-T2 Dual Port Gigabit Ethernet Adapter (Stony Lake T2)	Intel I350-T4 Quad Port Gigabit Ethernet Adapter (Stony Lake T4)	Intel Wi-Fi 6 AX201 2*2ax+BT5.0 vPro PCIE M.2 2230 Module (CNVi)	Intel Jefferson Peak 2 9560 2*2ac+BT5.0 PCIE Non-vPro M.2 Module (CNVi)	Foxconn RTL8822CE 2*2ac+BT5.0 PCIE M.2 WLAN module
Connector	2 x Ports RJ-45 Copper	4 x Ports RJ-45 Copper	Coming Soon	Coming Soon	Coming Soon
Website	i350 T2	i350 T4	Coming Soon	Coming Soon	Coming Soon
Auto-Negotiation	IEEE* 802.3* Auto-negotiaton	IEEE* 802.3* Auto-negotiaton	IEEE* 802.11ax* Auto-negotiaton	IEEE* 802.11ac* Auto-negotiaton	IEEE* 802.11ac* Auto-negotiaton
Intel® vPro™	Not Available	Not Available	Coming Soon	Coming Soon	Coming Soon
Intel® Stable Image Platform Program (SIPP)	Coming Soon		Coming Soon		Coming Soon
Intel® Standard Manageability	Supported	Supported	Coming Soon	Coming Soon	Coming Soon
Power Optimizer Platform Low-power Management Systems	Supported	Supported	Coming Soon	Coming Soon	Coming Soon
Energy Efficient Ethernet	Supported	Supported	Coming Soon	Coming Soon	Coming Soon
TCP/UDP Checksum and Segmentation Offload (IPv4 and IPv6)	Supported	Supported	Supported	Supported	Supported
Receive Side Scaling	Supported	Supported	Coming Soon	Coming Soon	Coming Soon
Dual Tx and Rx Queues	Yes	Yes	Coming Soon	Coming Soon	Coming Soon
Jumbo Frames (up to 9KB)	Supported	Supported	Coming Soon	Coming Soon	Coming Soon
Teaming	Supported	Supported	Coming Soon	Coming Soon	Coming Soon
Wake from Deep Sx	Supported	Supported	Coming Soon	Coming Soon	Coming Soon
Server Operating System Support	Windows Server 2008, 2012, 2016, 2019 Linux (RHEL/SLES),	Windows Server 2008, 2012, 2016, 2019 Linux (RHEL/SLES),	Windows 10, Linux, Chrome	Windows 8.1, Windows 10, Linux, Chrome	Windows 10

	Free BSD, Xen, Vmware	Free BSD, Xen, Vmware			
Network Proxy/ARP Support	Supported	Supported	Coming Soon	Coming Soon	Coming Soon

SECTION IV: BIOS / Certifications / Standards / Environmental

BIOS Specifications

WMI Support	Compliant with Microsoft WBEM and the DMTF common information model
ROM-Based Setup Utility (F1)	System configuration setup program (text/graphic interface) available at power-on with F1 key
Bootblock Recovery	Recovers system BIOS if the flash ROM is corrupted
Replicated Setup	Saves system configuration settings to a file that can then be used to replicate the settings to other systems
Boot Control	Boot control available through ROM-based setup utility or with F12 key at power-on
Memory Change Alert	Power-on error message in the event of a decrease in system memory
Thermal Alert	Power-on error message in the event of a fan failure
Asset Tag	Supports ability to set SMBIOS type 2 baseboard asset tag field
System/Emergency ROM Flash Recovery with Video	Supports process to recover the system BIOS if the flash ROM is corrupted
Remote Wakeup/Remote Shutdown	System admin can power on/off a client computer from a remote location to provide maintenance
Quick Resume Time	Supports low power S3 (suspend to RAM) and prompt resume times
ROM Revision Level	System UEFI (BIOS) version reported in SMBIOS type 0 structure and in BIOS setup
Keyboard-less Operation	System can be booted without a keyboard
Per-port Control	Allows I/O ports to be individually enabled/disabled through ROM-based setup or WMI interface
Adaptive Cooling	Offers multiple settings for fan control ranging between better performance and better acoustics
Security	Supervisor, user and power-on passwords can protect boot and ROM-based setup <ul style="list-style-type: none"> - Chassis Intrusion Detection - UEFI Secure Boot Support - HDD Password Can Protect HDD Data - Windows UEFI Firmware Update Support - Device Guard Support - BIOS Guard, Boot Guard Support
Intel(R) AMT (includes ASF 2.0)	Allows system to be supported from a remote location
Intel(R) TXT	Intel(R) trusted execution technology provides a security foundation to build protections against software based attacks
Memory Modes	Supports mirroring, lock step, and sparing memory modes
Windows 10 Ready	Supports Windows 10 requirements for secure flash, UEFI v 2.7 device guard support spec

Industry Standard Specification Support

UEFI	Unified Extensible Firmware Interface v2.7
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ACPI (Advanced Configuration and power Management Interface)	Advanced Configuration and Power Interface v6.2
ASF 2.0	DMTF Alert Standard Format Specification v2.0
ATA (IDE)	AT Attachment 6 with Packet Interface (ATA/ATAPI-6)
CD Boot	EI Torito Bootable CD-Rom Format Specification, v1.0
EHCI	Enhanced Host Controller Interface for Universal Serial Bus, Revision v1.0
PCI	PCI Local Bus v3.0 PC Firmware Specification 3.1
PCI Express	PCI Express Base Specification v3.0
SATA	Serial ATA Revision 3.0 Specification
TPM	Trusted Computing Group TPM Specification v2.0
UHCI	Universal Host Controller Interface Design Guide, Revision v1.1
USB	Universal Serial Bus Revision v1.1 Universal Serial Bus v2.0 Universal Serial Bus v3.0 Universal Serial Bus v3.2
SMBIOS	DMTF System Management Spec v3.2.1
XHCI	XHCI SPEC Revision v1.2

Social and Environmental Responsibility

Quality Control	Lenovo is a member of an eco declaration system that enforces regular independent quality control
Hazardous Substances and Preparation	<ul style="list-style-type: none"> • Products do not contain more than; 0.1% lead, 0.01% cadmium, 0.1% mercury, 0.1% hexavalent chromium, 0.1% polybrominated biphenyls (PBB) or 0.1% polybrominated diphenyl ethers (PBDE). (See legal reference and Note B1) • Products do not contain Asbestos • Products do not contain Ozone Depleting Substances: Chlorofluorocarbons (CFC), hydrobromofluorocarbons (HBFC), hydrochlorofluorocarbons (HCFC), Halons, carbontetrachloride, 1,1,1-trichloroethane, methyl bromide • Products do not contain more than; 0.005% polychlorinated biphenyl (PCB), 0.005% polychlorinated terphenyl (PCT) in preparation • Products do not contain more than 0.1% short chain chloroparaffins (SCCP) with 10-13 carbon atoms in the chain containing at least 48% per mass of chlorine in the SCCP • Parts with direct and prolonged skin contact do not release nickel in concentrations above 0.5 microgram/cm²/week <p>REACH Article 33 information about substances in articles is available at: https://www.lenovo.com/us/en/social_responsibility/social_responsibility_resources/</p>
Batteries	UN38.3,MSDS
Safety, EMC Connection to the Telephone Network and Labeling	Not applicable

Acoustic Noise Emissions Declaration

LWAd(bels) Idle	3.1
LWAd(bels) Oper	3.7

Safety, EMC Connection to the Telephone Network and Labeling

Industry Standard Specifications	not applicable
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Remote Manageability Software Solutions	not applicable
System Software Manager	Lenovo ThinkStation supports software management tools by Lenovo Vantage.

Regulations & Standards

EMC & Safety	FCC/IC VCCI BSMI KC RCM TUV-GS cTUVus IEC60950-1&IEC62368 CB Report/Certificate Saudi Arabia EQM Kuwait KUCAS China CCC Mark South Africa SABS Russia/Belarus/Kazakhstan/Kyrgyzstan/Armenia-EAC Morocco-CM Mexico-NOM Serbia KVALITET Ukraine UKrCEPRO India-BIS China SRRC Indonesia-SDPPI Malaysia-SIRIM Philippines-NTC
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Environmentals

Energy Star	ENERGY STAR 8.0
EPEAT	EPEAT Certification Available on Select Models
ErP Lot-3 2013	Yes
Hazardous Substances	<ul style="list-style-type: none"> • Products do not contain more than; 0.1% lead, 0.01% cadmium, 0.1% mercury, 0.1% hexavalent chromium, 0.1% polybrominated biphenyls (PBB) or 0.1% polybrominated diphenol ethers (PBDE) • Products do not contain Asbestos • Products do not contain Ozone Depleting Substances: Chlorofluorocarbons (CFC), hydrobromofluorocarbons (HBFC), hydrochlorofluorocarbons (HCFC), Halons, carbontetrachloride, 1,1,1-trichloroethane, methyl bromide • Products do not contain more than; 0.005% polychlorinated biphenyl (PCB), 0.005% polychlorinated terphenyl (PCT) in preparation • Products do not contain more than 0.1% short chain chloroparaffins (SCCP) with 10-13 carbon atoms in the chain containing at least 48% per mass of chlorine in the SCCP • Parts with direct and prolonged skin contact do not release nickel in concentrations above 0.5 microgram/cm_/week